



Material Content Data Sheet



Sales Product Name		BSZ100N03MS G		Issued		29. August 2013		
MA#		MA000896768						
Package		PG-TSDSON-8-21		Weight*		36.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.709	1.96	1.96	19581	19581
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65	
	non noble metal	zinc	7440-66-6	0.009	0.03		262	
	non noble metal	iron	7439-89-6	0.189	0.52		5231	
	non noble metal	copper	7440-50-8	7.689	21.24	21.80	212406	217964
	noble metal	gold	7440-57-5	0.217	0.60	0.60	6001	6001
wire	noble metal	gold	7440-57-5	0.217	0.60	0.60	6001	6001
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1035	
	plastics	epoxy resin	-	1.929	5.33		53290	
	inorganic material	silicondioxide	60676-86-0	16.762	46.32	51.75	463051	517376
	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10223	10223
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2232	2232
solder	non noble metal	tin	7440-31-5	0.051	0.14		1413	
	non noble metal	lead	7439-92-1	0.972	2.68	2.82	26840	28253
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		130	
	non noble metal	iron	7439-89-6	0.094	0.26		2596	
	non noble metal	copper	7440-50-8	3.816	10.54	10.81	105415	108173
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.078	0.22		2165	
	non noble metal	copper	7440-50-8	3.182	8.79	9.02	87897	90197
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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